

WHAT IS CLAIMED AS NEW AND IS INTENDED TO BE SECURED BY LETTER  
PATENT IS:

1. A microencapsulated adhesive component, comprising:

5        a cross-linking constituent microencapsulated with a silanized polybutadiene, wherein  
the reactive constituent has been first reacted in the melt with cross-linking, thereby resulting  
in a cross-linkable hot-melt adhesive component for coating and/or laminating surface  
formations.

10        2. The microencapsulated adhesive component as claimed in Claim 1, wherein the  
cross-linking constituent is micro-encapsulated with a silanized polybutadiene in a ratio of  
4:1.

15        3. The microencapsulated adhesive component as claimed in Claim 1, wherein the  
silanized polybutadiene has a silicon content of 2 to 10% by weight, a molecular weight of  
1500 to 2500 g/mol and a viscosity of 1000 to 3000 mPas.

20        4. The microencapsulated adhesive component as claimed in Claim 1, wherein the  
cross-linking constituent is an isocyanate compound which has more than two reactive  
groups per molecule.

25        5. The microencapsulated adhesive component as claimed in Claim 1, wherein the  
isocyanate compound has a melting range of 110 to 130°C.

6. The microencapsulated adhesive component as claimed in Claim 1, wherein the  
cross-linking constituent is an isocyanate which is micro-encapsulated with a silanized  
polybutadiene and which reacts with a second constituent which is a copolyamide or  
copolystyrene.

7. The microencapsulated adhesive component as claimed in Claim 6, wherein the  
second constituent is an amine-regulated copolyamide with a melting range of 90 to 150°C  
and a solution viscosity or relative melting viscosity  $\eta/c$  in the range of 1.2 to 1.7.

8. The process as claimed in Claim 6, wherein the second constituent is an OH group terminated copolyester prepared from terephthalic acid, isophthalic acid and butanediol or butanediol in combination with small quantities of up to 12 mole % of another diol, having a melting point of 100 to 150°C.

5           9. An aqueous printing paste, comprising:  
the microencapsulated cross-linking constituent of Claim 1 dispersed in an aqueous  
paste.

10. The printing paste according to Claim 9, wherein the paste further comprises an acid catalyst, a commercial surfactant, a defoaming agent, a thickener and water.

11. The printing paste according to Claim 10, wherein the aqueous paste is applied to a substrate by rotary screen printing.

12. An aqueous printing paste, comprising:  
the microencapsulated cross-linking constituent of Claim 1 combined with a second constituent of a copolyamide or a copolyester dispersed in an aqueous paste.

13. A method of bonding surfaces, comprising:  
applying the paste of Claim 9 onto a surface as the base dots of double dot technology as a strike back barrier;  
applying, as the upper dot component of the double dot process, an amine regulated copolyamide; and  
20           effecting bonding between the materials of the applied dots.

14. A process, comprising:  
micro-encapsulating a cross-linking constituent in a silanized polybutadiene, thereby resulting in a cross-linkable hot-melt adhesive component for coating and/or laminating  
25           surface formations.